

# SOT391B

flangeless ceramic package; 2 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	CDFM2
<b>Package type industry code</b>	CDFM2
<b>Package style descriptive code</b>	CDFM (ceramic double-ended flange mount)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	C (ceramic)
<b>Mounting method type</b>	H (heatsink mount)
<b>Issue date</b>	29-5-1997

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.51	-	11.025	11.54	mm
E	package width	9.9	-	10.415	10.93	mm
A	seated height	3.02	-	3.555	4.09	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

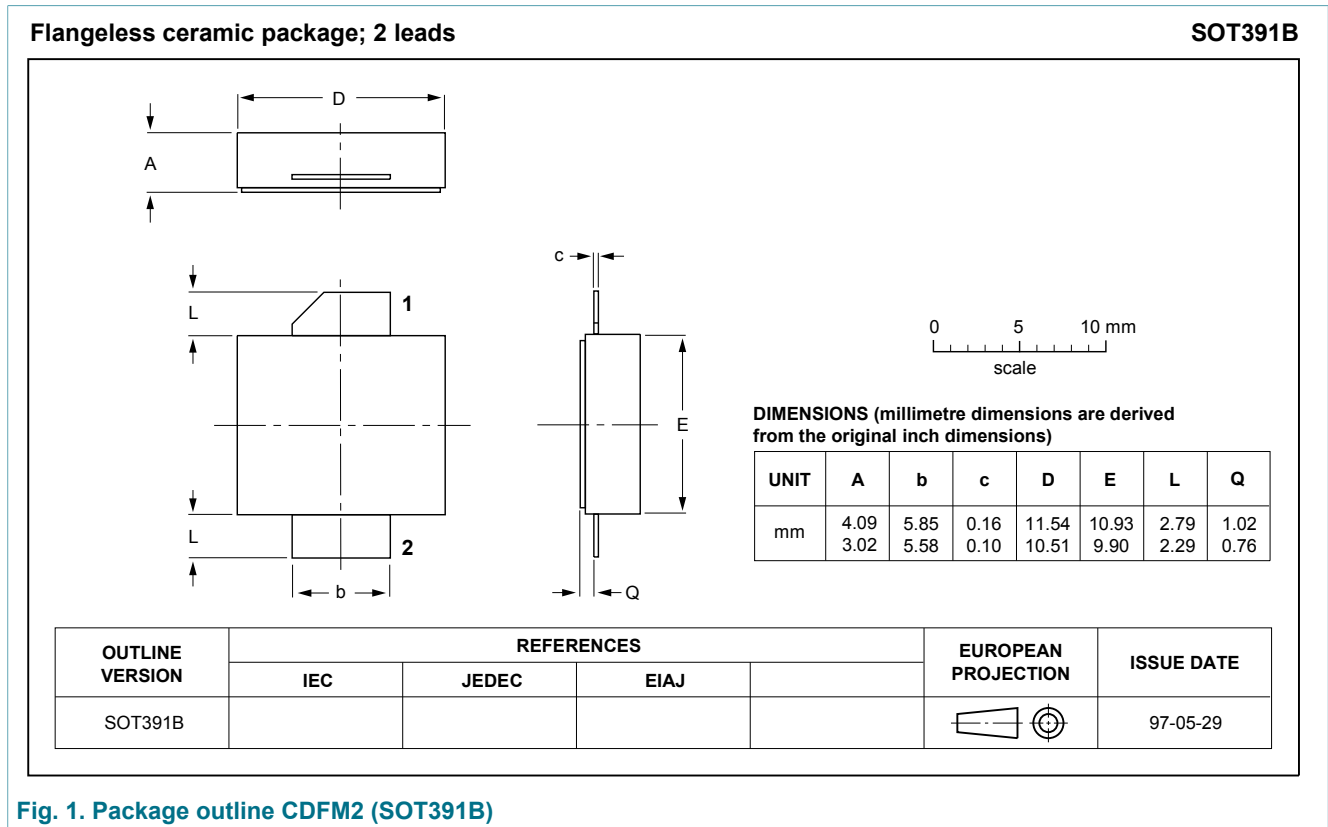


Fig. 1. Package outline CDFM2 (SOT391B)

### 3. Legal information

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